

Specific questions exemption 14

“Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80 % and less than 85 % by weight”

The following specific questions should be answered in your stakeholder contribution if you support exemption 14 to be continued / amended / discontinued:

1. Please state the **amount of lead** used per application, the lead content in the homogeneous material, the annual production volume as well as the number of applications related to exemption 14 put on the EU market annually.
2. Please explain the status of lead-free material use in this application (Where is substitution feasible? Where is substitution in progress? Where has research resulted in an unfeasibility of substitution? ...).
3. The previous evaluation in 2004 stated that design changes would make this exemption obsolete by 2010. The exemption should therefore be limited to 31 December 2009. Is such a **phase out** still possible until the end of 2009? If the exemption is needed beyond 2009, please justify and provide a detailed **roadmap** with activities, milestones and timelines towards the replacement of lead in this application. Name an **expiry date** that you think is technologically feasible for industry.